



Material Composition Declaration

EPC2204

Company Name	Efficient Power Conversion (EPC)	Issue Date:	9/9/2020
Contact Name:	Yanping Ma	Contact Title:	VP Quality
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Part Weight:	5.9 mg	Type of Product:	eGaN FET

Construction Element	Substance	CAS No. If Applicable	Weight	Mass	Sum	Mass
			(mg)	(%)	(%)	(ppm)
Chip	Silicon	7440-21-3	4.4368	74.7904	77.3689	747904
	Silicon oxide	7631-86-9	0.0147	0.2478		2478
	Silicon nitride	12033-89-5	0.0087	0.1467		1467
	Gallium nitride	25617-97-4	0.0211	0.3562		3562
	Aluminum	7429-90-5	0.0582	0.9816		9816
	Aluminum nitride	24304-00-5	0.0048	0.0807		807
	Titanium	7440-32-6	0.0008	0.0138		138
	Titanium nitride	25583-20-4	0.0056	0.0951		951
	Copper	7440-50-8	0.0019	0.0327		327
	Tungsten	7440-33-7	0.0022	0.0372		372
	Polyimide		0.0348	0.5867		5867
Under Bump Metal	Titanium	7440-32-6	0.0007	0.0113	0.1240	113
	Nickel	7440-02-0	0.0000	0.0000		0
	Copper	7440-50-8	0.0067	0.1127		1127
Solder Bump	Copper	7440-50-8	0.0669	1.1269	22.5071	11269
	Nickel	7440-02-0	0.0399	0.6722		6722
	Tin	7440-31-5	1.2063	20.3352		203352
	Silver	7440-22-4	0.0221	0.3727		3727
Sum in total:			5.9322	100.0000	100.0000	1000000

Note:

The substance content disclosed herewith is approximate and is based on engineering calculation. Statements are based on our present knowledge and may subject to change at any time due to technical requirements and development. EPC may update this document without notification. Statement may not include information regarding the minute quantities of dopant and metal materials in the electrical devices contained within the finished product.